

HTPA60x40dR1L1.4/0.8

Datasheet for Thermopile Array Sensor with Lens Optic

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Changelog

2021-01-30	Order code; change note implementation; EEPROM link to microchip
2021-11-08	Corrected pinout
2021-11-23	Updated drawing
2022-01-03	Updated EEPROM Map; corrected Readout order, changed several Formulas
2022-04-21	Corrected graph for SPI Timings
2022-07-05	Updated drawing
2022-08-01	Corrected pinout; several small changes
2022-10-10	Updated schematics for L4.0/0.8F7.6
2023-03-30	Updated dimensions for L1.9
2023-11-14	Note on the use of the SPI pin added
2024-01-08	Added Section for Integrated Flash Memory (HS-Flash)
2024-03-25	Change in nomenclature
2024-05-08	Added a handling notice for internal flash memory
2024-11-11	Updated drawing for HTPA60x40dL1.9UHiC
2024-12-16	Updated graphic for optical orientation.
2025-01-31	Updated order code, added order code chart w/ available options
2025-02-19	Corrected specifications for lens coating for HTPA60x40dR1L4.0/0.8F6.0
2025-02-25	Updated storage and operating temperature
2025-03-18	Updated technical drawings w/ added measurements for L1.9 and L4.0
2025-04-02	Corrected storage temperature
2025-04-22	Corrected pin allocations
2025-05-13	Updated maximum framerate
2025-06-10	Corrected pin numbering in the pin assignment section
2025-07-09	Added preliminary radiometric radius for L0.9 and L1.4
2025-08-18	Corrected graphic for pixel orientation; adjusted graph for NETD vs Pixel Distance
2025-10-16	Added max. measurable temperature
2025-11-18	Corrected accuracy specification

2025-12-11	Corrected several instances where EEPROM was incorrectly referenced instead of flash
2025-03-02	Added calculation formula for CLK_Trim Register

1 Important Handling Notice for the Internal Flash Memory

To ensure the stability and functionality of the flash memory, it is extremely important to read and follow the instructions below. **Failure to do so may result in the loss of memory content:**

- Absolutely **no hot plugging** – always plug the sensor into a de-energized socket!
- Use the adequate library – usage of wrong code can cause a reset of the flash. For example, the libraries for a HTPAd device with an EEPROM will delete the flash permanently!
- Do not unplug the sensor during communication!
- In case of voltage drop: Try to stop communication to the flash immediately, especially during a brown out.
- At initialization of the IOs make sure the *SSEL pin* is initialized as soon as possible and keep the status high immediately to make sure there is no traffic to the flash memory during the initialization of the pins!
- Do not flash the master board while the sensor is inserted!

2 Cleaning and Handling of Sensors with Optical Elements

Cleaning of Filter with Isopropyl Alcohol or Acetone

This is the method most universally used for cleaning optical elements with or without coatings. Filters or lenses mounted in our sensors may be cleaned rubbing the surfaces lightly with a clean, soft, all-cotton cloth or cotton swab during immersion in solvent or simply moistened with the solvent. The parts are then immediately wiped dry with another clean, soft, all-cotton cloth or cotton swab.

Cleaning with Detergent and Water

A very mild, non-abrasive detergent (one which does not contain additives) and water may also be used for cleaning optical elements. In general, a detergent and water mixture is an excellent method for removing fingerprints and other smudges. The liquid detergent is first mixed with deionized water (proportions recommended by the manufacturer should be followed). The element is then washed, rinsed, and immediately wiped dry. Use a clean, soft cloth when cleaning and drying. If the part is allowed to dry in air, a permanent stain may result.

Please note:

- Do not use isopropyl alcohol or acetone or detergent if the elements will be mounted in an assembly with a finish which may be soluble by these solvents.
- Please avoid glass isolation being moistened by solvent.
- If the part is allowed to dry in air, a permanent stain may result.

Handling Advice

Sensors with optical elements deserve special consideration in their handling and care. Ordinarily, filters or lenses are cleaned and inspected prior to shipment. If proper care is exercised during handling cleaning should not be necessary prior to use.

- Wear gloves when handling a sensor or optical element. Lightweight nylon or cotton gloves which are relatively lint-free are recommended.
- Avoid touching the surface of filters and lenses.
- Protect devices from static discharge and static fields.
- Thermopile sensors are electrostatic sensitive devices. Sensors should be handled over an electrostatic protected work area.
- Precautions should be taken to avoid reverse polarity of power supply for sensors with integrated signal processing. Reversed polarity of power supply results in a destroyed unit.
- Sensors should rest preferably in a partitioned container where the mounted filters or lenses will be not coming into contact with other material.
- During storage optical surfaces should be covered to avoid contamination from the surrounding environment.
- A covered container can eliminate damage during transportation and storage.
- Sensors or optical elements should be stored in a restricted access area to eliminate handling.
- Do not expose the sensors to aggressive detergents such as freon, trichlorethylen, etc.
- Avoid rotating the sensors when they are soldered into a PCB or something similar.
- Shortening of the pins is not suggested. This may cause cracks in the glass of the pins and result in a leakage.
- If this is necessary, a tool for this is recommended. Please contact Heimann Sensor for further information.

Soldering Recommendations

Attention: For all of our array sensors we give no guarantee on the calibration and its performance, if the pins are shortened by the customer. Additionally, **we strongly recommend to not solder the sensor with its backplate directly to a PCB.** This will cause different thermal conductivity compared to air and the measurement results could get worse. **Use a minimum gap between PCB and backplate of 2 mm or more.** The glass of the pins to the back plate can get damage by applying high temperatures (during soldering), which will lead into a lower temperature reading what cannot be repaired afterwards.

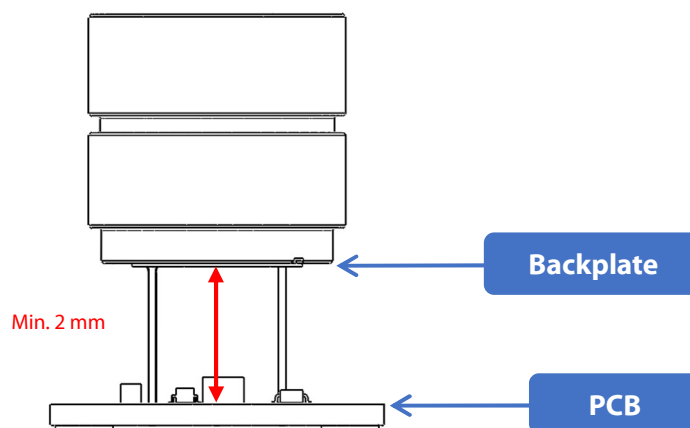


Figure 1: Soldering height

Manual Iron Soldering and Automatic Point-to-Point Iron Soldering

Manual Iron Soldering and Automatic Point-to-Point Iron Soldering methods are allowed for TO packages. It is recommended for through hole applications to shield the package body from soldering heat by PCB or similar.

The soldering iron temperature should be set as low as possible (maximum 350 °C) and should not exceed recommended soldering time (maximum 3 seconds). The minimum distance between the housing body and the liquid solder should be at least 1.5 mm for 350 °C. Reflow soldering is not recommended.

3 Principal Schematic for HTPA60x40d

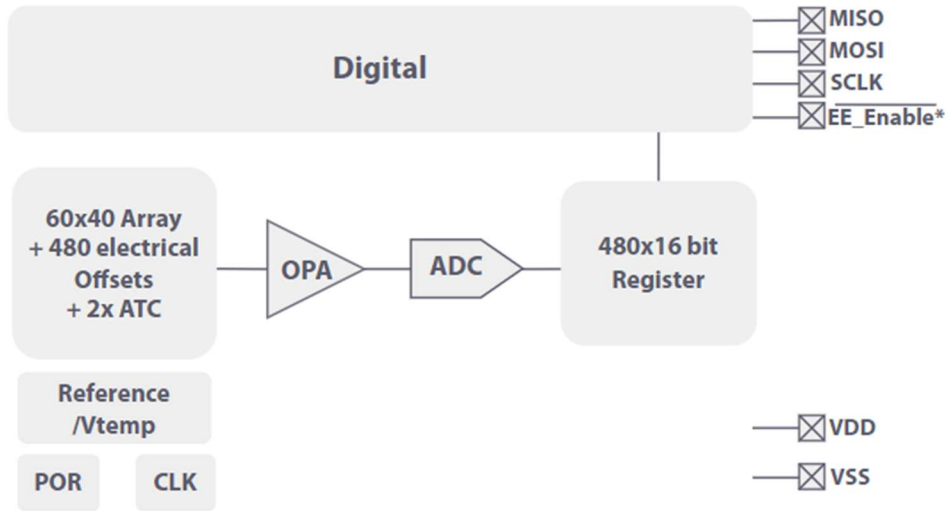


Figure 2: Schematic for HTPA60x40d

* EE_Enable : The slave select is used to switch communication between sensor and flash.

The ATC is an Ambient Transient Compensation, which can be used for heat-shock compensation.

4 Pin Assignment – Bottom View

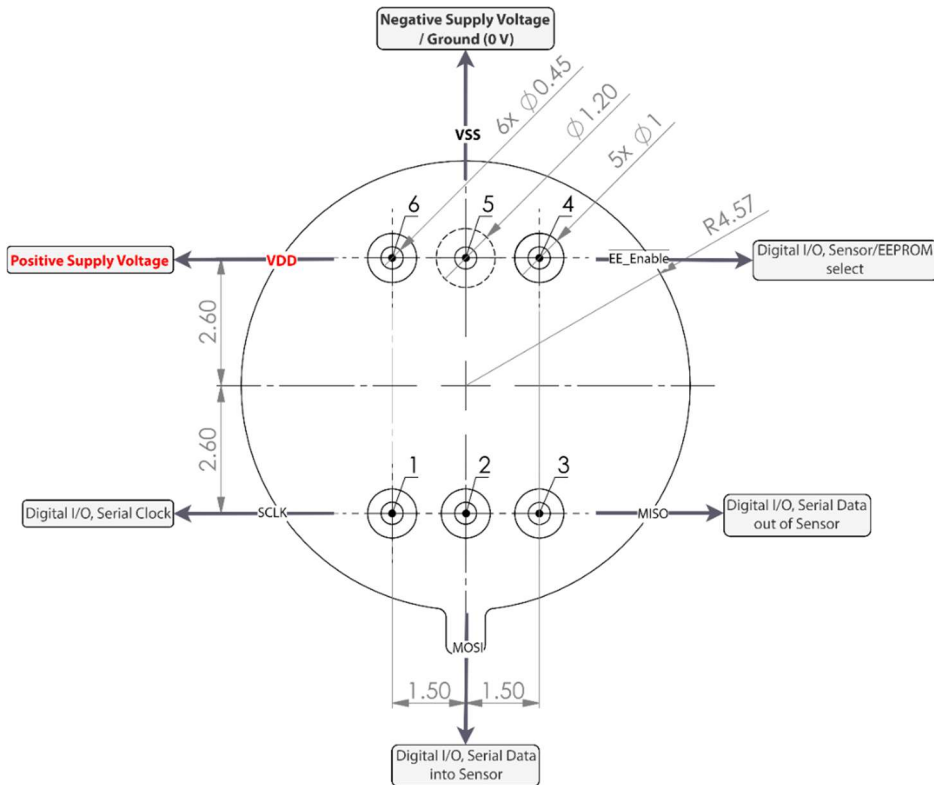
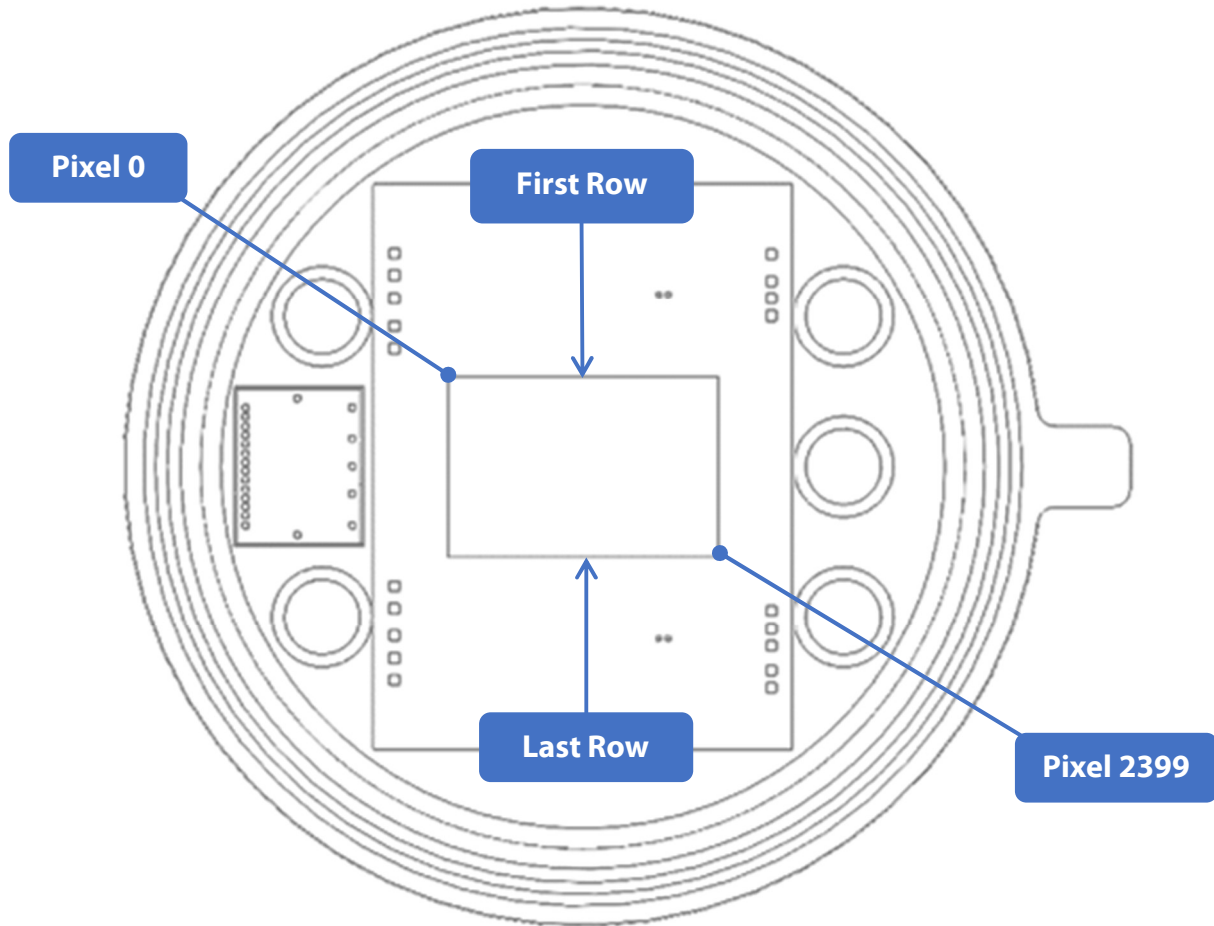
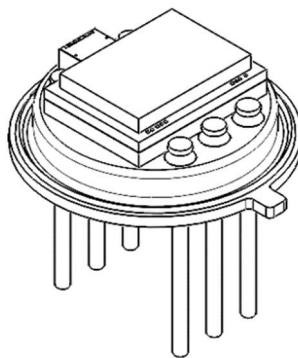


Figure 3: Pin-allocation

5 Optical Orientation



This illustration shows the pixel orientation after mirroring through the lens.



6 Order Code Example

HTPA32x32d	R2	L5.0/0.85	F7.7	e	Hi	M	(UDP)
1	2	3	4	5	6	7	8

		Description
1	Sensor Type	TP Array with 32x32 Pixel For all available HTPA and module combinations contact our support
2	Revision	Silicon revision 2
3	Optics	Focal length/F-Number Focal length: L5.0 = 5.0 mm F-Number: 0.85
4	Filter	F: Filter characteristics Not declared: Broadband AR Coating
5	External Aperture	Not declared: without external aperture e: with external aperture
6	Sensitivity	UHi: increased sensitivity Hi: default sensitivity Not declared: lower sensitivity (greater measurement range)
7	Version	A: Application Set: comes with GUI, housing, power supply C: Calibrated sensor M: Modul: HTPA sensor soldered to PCB, calibrated stream
8	Interface	UDP: Ethernet connection, CAT5 PoE: Power over Ethernet, CAT5* i ² C: 4 Pin Connector* USB: Power and data via USB 2.0** * Interface option is only available for modules (HiM) ** Interface option is only available for Application Set (HiA)

7 Application Note

This Application Note is giving a short recommendation for the connection of the HTPA60x40d to achieve the best performance. Adding 100 nF and 47 μ F are improving the stability of the supply voltage.

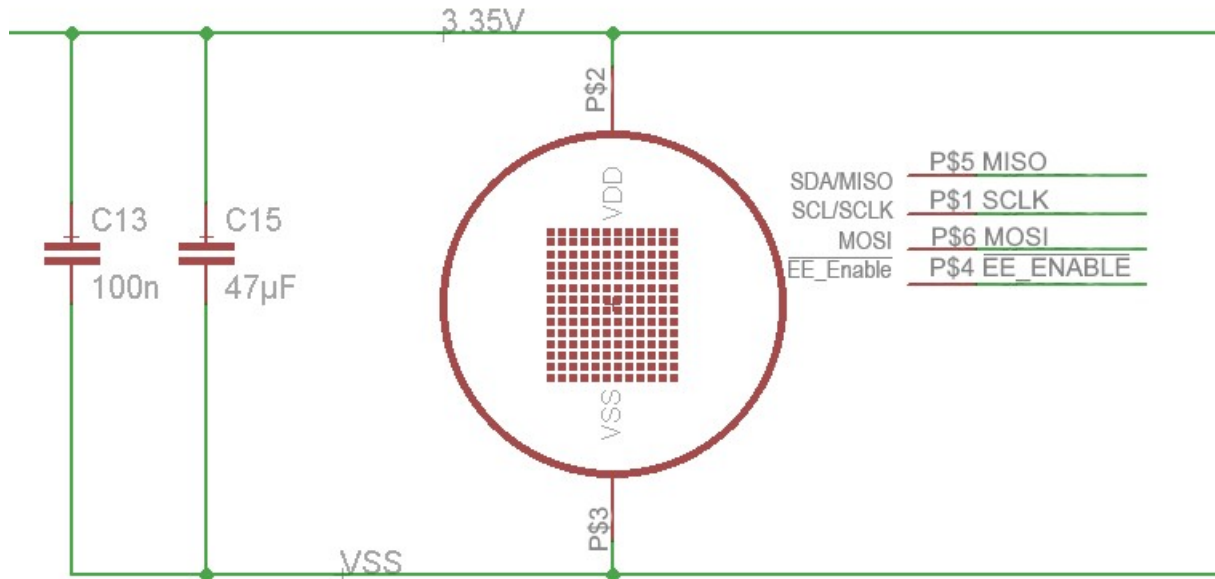


Figure 4: Recommended circuit for operation

The Sensor can be powered directly via 3.35 V if the supply voltage is stable enough, this has to be measured before and tested with the sensor. It is important to not insert any inductor or otherwise the noise will increase.

8 Serial Order of Frame

The sensor is divided into two parts (top and bottom half), which are again separated into 5 blocks. The readout order is shown below for the different blocks.

Block 0 (top)
Block 1 (top)
Block 2 (top)
Block 3 (top)
Block 4 (top)
Block 4 (bottom)
Block 3 (bottom)
Block 2 (bottom)
Block 1 (bottom)
Block 0 (bottom)

Figure 5: Division of blocks

Whenever a conversion is started the block x of the top and bottom half are measured at the same time. Each block consists of 240 Pixel that are sampled fully parallel. The readout order on the bottom half is mirrored compared to the top half, so that the central lines are always read last.

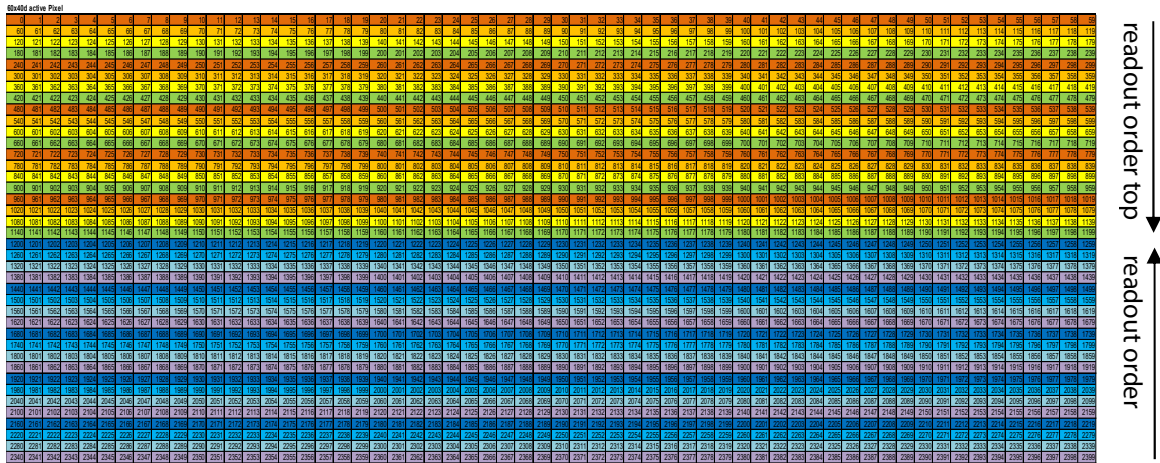


Figure 6: 60x40d readout order for active pixel

The electrical offsets are sampled according to the top and bottom half. The matching rows for the corresponding electrical offsets and active Pixel are marked with the same color. The conversion of the electrical offsets is started by setting the BLIND bit during the start command.

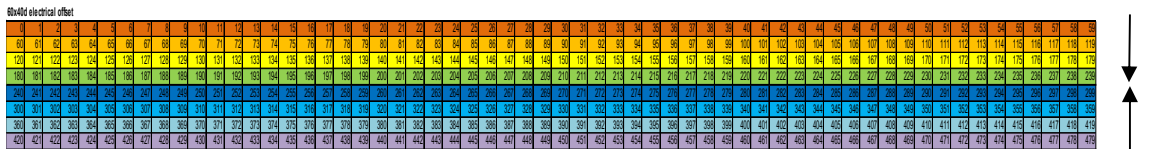


Figure 7: 60x40d readout order for electrical offset

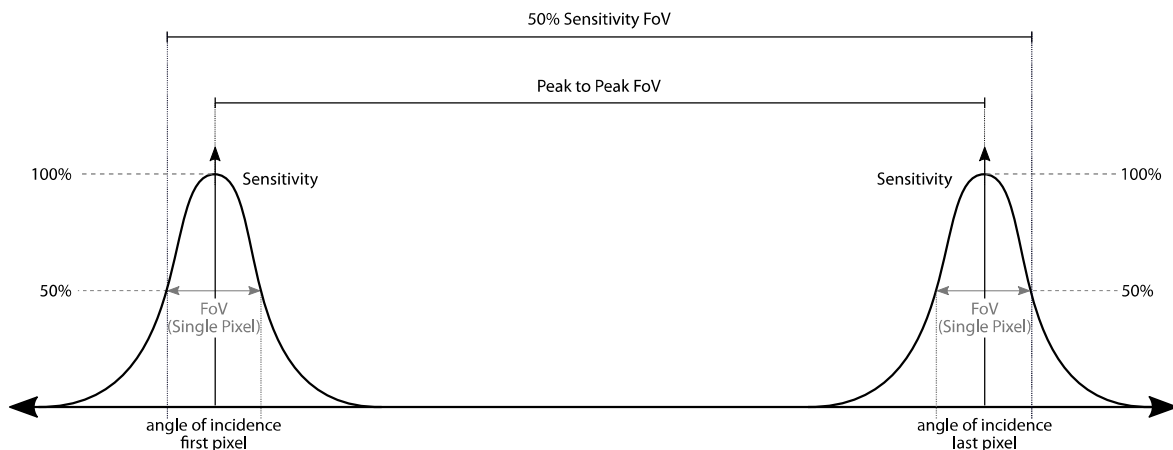
9 Characteristics

9.1 Common Specifications

Technology:	n-poly/p-poly Si
Thermal pixel time constant:	TBD
Digital Interface:	SPI
NVM size:	512 kBit
Pitch:	45 μm
Absorber size:	40 μm
Max. Framerate:	35 Hz
Max. measurable temperature:	TBD
(Complete frame with maximum SPI, sensor clock speed and reduced ADC resolution)	
2400 sensitive elements	

9.2 Optical Characteristics

Focal length:	1.4 mm ("L" equals the focal length of the lens)
F-Number:	0.8
Field of view:	120 x 68 deg. (50 % sensitivity FoV) preliminary



Lens coating:	AR-Coating
Accuracy:	Sensor in prototype status, final accuracy will be specified in series status

The radiometric radius is specified for pixels listed below with a "1". All pixels outside this area can have a higher tolerance and less accuracy.

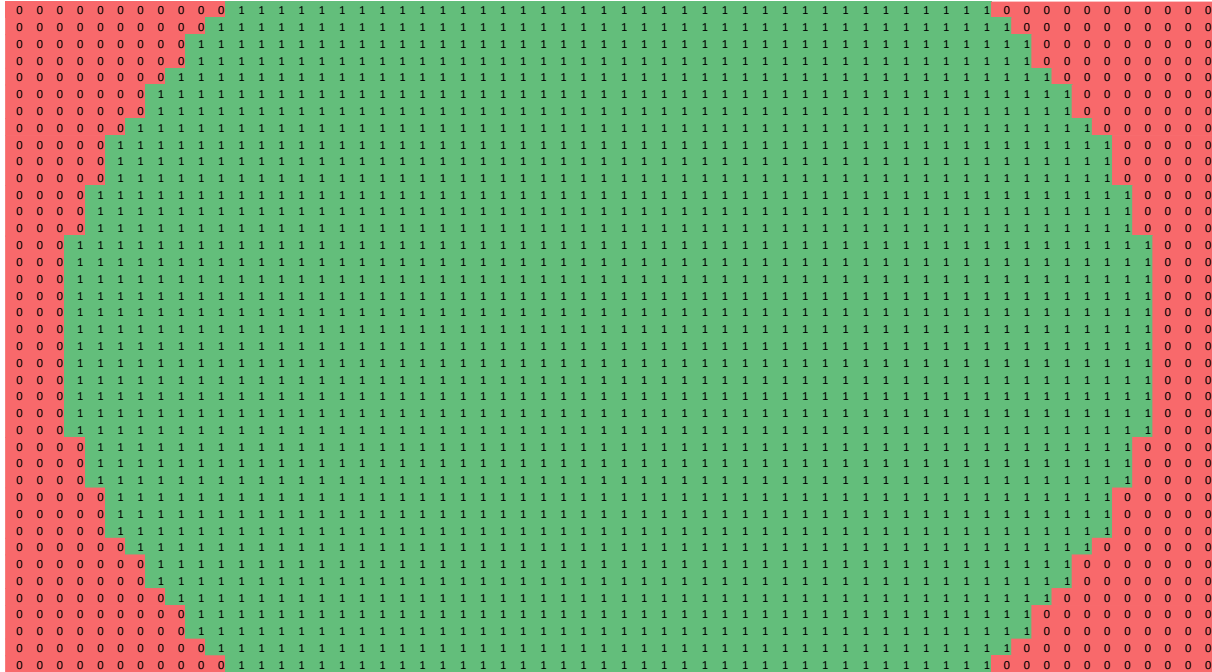


Figure 8: PRELIMINARY Radiometric radius in a matrix of 60x40 pixels

10 Electric Specifications

Table 1: Absolute Maximum Ratings

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Supply Voltage	V _{DD}		-0.3		3.6	V
Voltage at all inputs and outputs	V _{IO}		-0.3		V _{DD} +0.3	V
Storage Temperature	T _{STG}		-20		60	Deg. C

Table 2: Operating Conditions

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Supply Voltage	V _{DD}		3.3	3.35	3.6	V
Supply Current (sensor running)	I _{DD}		5.5	6	7.5	mA
Supply Current (sensor in idle state)	I _{DD}		4	4.5	6	mA
Standby Current (sensor in sleep state)	I _{SBY}		7.5	9.5	11.5	μA
Operation Temperature	T _A		-20		60	Deg. C
ESD-Protection		Human body model	2.0			kV
		100pF + 1k50hm				

Table 3: Electrical Characteristics

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Digital Input						
Internal Clock frequency	F _{CLK}		0.5	2.17	5.5	MHz
BIAS current	I _{BIAS}		1	5	13	μA
Input voltage high	V _{IH}		0.7xV _{DD}			V
Input voltage low	V _{IL}				0.3xV _{DD}	V
PTAT						
Temperature range			TBD		TBD	Deg. C
PTAT gradient			TBD	TBD	TBD	K/V

Table 4: Preamplifier / ADC

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Chopper frequency	F_{CHP}			40		kHz
Preamplifier Noise	N_{PA}	at 40 kHz		72		nV/Hz ^{1/2}
Frame rate (Full Array)	FR1		5.6	21.2	35	Hz
Frame rate (1/5 Array)	FR5		28	106	175	Hz
ADC pos. Reference	V_{REFP}	REF_CAL 00		1.65		V
		REF_CAL 01		1.55		
		REF_CAL 10		1.46		
		REF_CAL 11		1.36		
ADC neg. Reference	V_{REFN}	REF_CAL 00		0.87		V
		REF_CAL 01		0.79		
		REF_CAL 10		1.07		
		REF_CAL 11		1.17		
ADC resolution	ADC_{LSB}	at 16 Bit	5.8		23.8	μV

11 SPI Timings HTPA60x40d

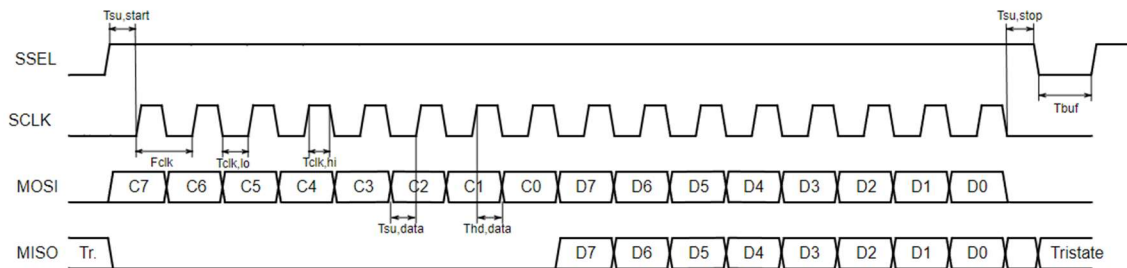


Figure 9: SPI Timings HTPA60x40d

Table 5: SPI Timings

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
SPI clock frequency	F_{CLK}		10		MHz
Low pulse duration	$T_{\text{CLK,lo}}$	30			ns
High pulse duration	$T_{\text{CLK,hi}}$	40			ns
Data set up time	$T_{\text{SU,data}}$	30			ns
Data hold time	$T_{\text{HD,data}}$	10			ns
Start setup time	$T_{\text{SU,start}}$	50			ns
Stop setup time	$T_{\text{SU,stop}}$	50			ns
Time between STOP/ START	T_{buf}	200			ns
Time startup (after Power-on Reset)	T_{startup}			100	μs
Time wakeup (after sending WAKEUP)	T_{wakeup}			80	μs

11.1 SPI Communication

The chip uses the 8-bit command for accessing configuration and sensor data.

The $\overline{EE_Enable}$ pin is utilized to switch the communication between sensor and internal non-volatile memory. Due to the need to toggle the $\overline{EE_Enable}$ pin the sensor with integrated EEPROM/FLASH requires a separate SPI interface. No other parts should use the same SPI lines in order to make sure that the parts can be selected correctly during communication.”

11.2 Write Command

In case of a write access to an internal register the command is followed by the data byte.

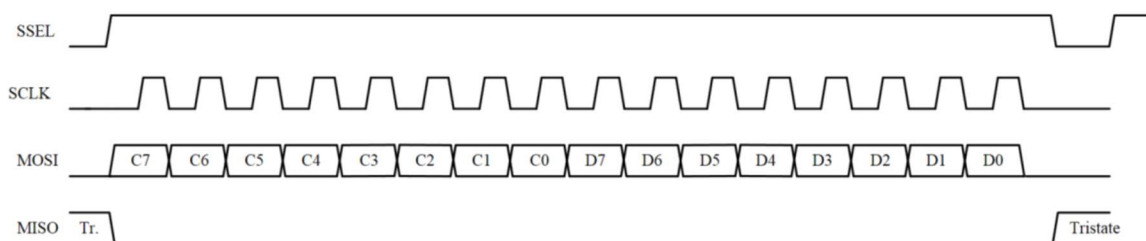


Figure 10: Write Command

11.3 Read Command

To read data from the chip first the read command must be sent. The command initiates the read sequence and the first bit of read bytes will be set on MISO with falling edge of SCLK after last command bit. There can be as many byte reads as required.

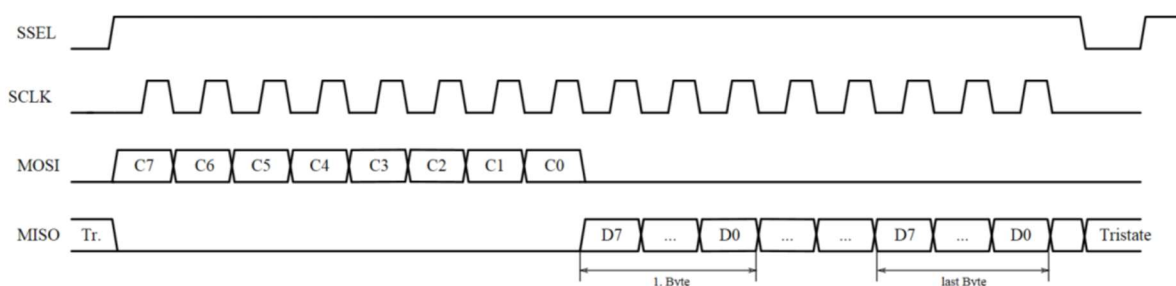


Figure 11: Read Command

11.4 Sensor Commands

The sensor has several registers that can be written and read, they are listed below.

Table 6: Configuration register (write only)

Addr / CMD	0x01							
Config Reg	7	6	5	4	3	2	1	0
Name	BLOCK				START	RFU	BLIND	WAKEUP
Default	0	0	0	0	0	0	0	0

The WAKEUP bit is used to switch on / off the chip and must be set prior all other operations. After the START bit is set the chip starts a conversion of the array or blind elements and enters the idle state (not sleep!) when finished. The BLOCK selects one of the five multiplexed array blocks.

If the BLIND bit is set the electrical offsets are sampled instead of the active pixel and the setting of the BLOCK is ignored.

RFU means reserved for future use and can be subject to change.

Table 7: Status Register (read only)

Addr / CMD	0x02							
Status Reg	7	6	5	4	3	2	1	0
Name	BLOCK				START	RFU	BLIND	EOC
Default	0	0	0	0	0	0	0	0

If the EOC flag is set a previous started conversion has been finished.

Table 8: Trim Register 1 (write only)

Addr / CMD	0x03							
Trim Reg 1	7	6	5	4	3	2	1	0
Name	RFU		REF_CAL		MBIT TRIM			

REF_CAL: selectable amplification

MBIT_TRIM: $m = 4$ to $12 \Rightarrow (m+4)$ bit as ADC resolution

Table 9: Trim Register 2 (write only)

Addr / CMD	0x04							
Trim Reg 2	7	6	5	4	3	2	1	0
Name	RFU			BIAS TRIM TOP				

BIAS_TRIM_TOP: 0 to 31 $\Rightarrow 1 \mu\text{A}$ to $13 \mu\text{A}$

This setting is used to adjust the BIAS current of the ADC. A faster clock frequency requires a higher BIAS current setting.

Table 10: Trim Register 3 (write only)

Addr / CMD	0x05							
Trim Reg 3	7	6	5	4	3	2	1	0
Name	RFU			BIAS TRIM BOT				

BIAS_TRIM_BOT: 0 to 31 $\Rightarrow 1 \mu\text{A}$ to $13 \mu\text{A}$

This setting is used to adjust the BIAS current of the ADC. A faster clock frequency requires a higher BIAS current setting.

Table 11: Trim Register 4 (write only)

Addr / CMD	0x06							
Trim Reg 4	7	6	5	4	3	2	1	0
Name	RFU		CLK TRIM					

CLK_TRIM ranges from 0 to 63 and corresponds the clock frequency F_{CLK} which can be determined via the following formula:

$$F_{CLK} = \left(F_{CLK,min} + \frac{F_{CLK,max} - F_{CLK,min}}{63} \cdot CLK_TRIM \right) \text{ MHz}$$

with

$$F_{CLK,min} = 0.5 \text{ MHz}$$

$$F_{CLK,max} = 5.5 \text{ MHz}$$

The measure time depends on the clock frequency settings. One quarter frame takes about:

$$t_{conv} \approx \frac{4 \cdot (2^{MBIT} + 100)}{F_{CLK}} \approx 7,73 \text{ ms @ 2.16 MHz}$$

$MBIT$ is equal to MBIT TRIM in Table 8.

Table 12: Read Data 1 Command (Top Half of Array)

Addr / CMD	0x0A							
Read Data	7	6	5	4	3	2	1	0
1. Byte / 2. Byte	ATC 1 MSB / LSB							
3. Byte / 4. Byte	PTAT 1 MSB / LSB							
5. Byte / 6. Byte	VDD 1 MSB / LSB							
7. Byte / 8. Byte	Pixel (0 + Block*240) MSB / LSB							
9. Byte / 10. Byte	Pixel (1 + Block*240) MSB / LSB							
...	...							
485. Byte / 486. Byte	Pixel (239 + Block*240) MSB / LSB							

The ATC is an Ambient Transient Compensation, which can be used for heat-shock compensation.

Table 13: Read Data 2 Command (Bottom Half of Array)

CMD	0x0B							
Read Data	7	6	5	4	3	2	1	0
1. Byte / 2. Byte	ATC 2 MSB / LSB							
3. Byte / 4. Byte	PTAT 2 MSB / LSB							
5. Byte / 6. Byte	VDD 2 MSB / LSB							
7. Byte / 8. Byte	Pixel (2340 - Block*240) MSB / LSB							
9. Byte / 10. Byte	Pixel (2341 - Block*240) MSB / LSB							
...	...							
125. Byte / 126. Byte	Pixel (2399 - Block*240) MSB / LSB							
127. Byte / 128. Byte	Pixel (2280 - Block*240) MSB / LSB							
129. Byte / 130. Byte	Pixel (2281 - Block*240) MSB / LSB							
...	...							
245. Byte / 246. Byte	Pixel (2339 - Block*240) MSB / LSB							
247. Byte / 248. Byte	Pixel (2220 - Block*240) MSB / LSB							
...	...							
485. Byte / 486. Byte	Pixel (2219 - Block*240) MSB / LSB							

The complete sensor data must be read at once. If the communication fails somewhere in between, all successive data will be corrupted. The readout can be stopped anywhere. A new initialized readout proceeds at this stopped byte, but the index is reset when a new conversion has been started.

If the bit for the electrical offsets (Bit 1 in Config 0x01) is set the electrical offsets are sampled and can be read similar to the active pixel:

Table 14: Read Data electrical offsets (Top Half of Array)

CMD	0x0A							
Read Data	7	6	5	4	3	2	1	0
1. Byte / 2. Byte	ATC 1 MSB / LSB							
3. Byte / 4. Byte	PTAT 1 MSB / LSB							
5. Byte / 6. Byte	VDD 1 MSB / LSB							
7. Byte / 8. Byte	electrical offset (0) MSB / LSB							
9. Byte / 10. Byte	electrical offset (1) MSB / LSB							
...	...							
485. Byte / 486. Byte	electrical offset (239) MSB / LSB							

Table 15: Read Data electrical offsets (Bottom Half of Array)

CMD	0x0B							
Read Data	7	6	5	4	3	2	1	0
1. Byte / 2. Byte	ATC 2 MSB / LSB							
3. Byte / 4. Byte	PTAT 2 MSB / LSB							
5. Byte / 6. Byte	VDD 2 MSB / LSB							
7. Byte / 8. Byte	electrical offset (420) MSB / LSB							
9. Byte / 10. Byte	electrical offset (421) MSB / LSB							
...	...							
125. Byte / 126. Byte	electrical offset (479) MSB / LSB							
127. Byte / 128. Byte	electrical offset (360) MSB / LSB							
129. Byte / 130. Byte	electrical offset (361) MSB / LSB							
...	...							
245. Byte / 246. Byte	electrical offset (419) MSB / LSB							
247. Byte / 248. Byte	electrical offset (300) MSB / LSB							
...	...							
485. Byte / 486. Byte	electrical offset (299) MSB / LSB							

The complete sensor data must be read at once. If the communication fails somewhere in between, all successive data will be corrupted. The readout can be stopped anywhere. A new initialized readout proceeds at this stopped byte, but the index is reset when a new conversion has been started.

12 Integrated Flash Memory

12.1 Absolute Maximum Ratings

Table 16: Absolute Maximum Ratings

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Storage Temperature	TST		-40		85	°C
Supply Voltage	VDD		-0.3		3.6	V
Supply Current	IDD				10	mA
Input Voltage Analog	VINA		-0.3		VDD + 0.3	V
Input Voltage Digital	VIND		-0.3		VDD + 0.3	V
ESD Protection Voltage	VESD	EN 61340-3-1 (HBM)	+/-2			kV

(1) All voltage values are with respect to network ground terminal.

(2) Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other condition beyond those indicated under operating conditions is not implied.

(3) Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

12.2 Operating Conditions

Table 17: Operating Conditions

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Operating Temperature	T _{OP}	write operation read operation	-20 -40		85 85	°C
Supply Voltage	V _{DD}		3.0	3.3	3.6	V
Supply Current	I _{DD,WR}	write	3.5		5.0	mA
Supply Current	I _{DD,RD}	read @ 20MHz		3.0		mA
Active Current	I _{ACT}			350		µA
Standby Current	I _{SBY}	PU / PD current is not included		110	150	µA
Powerdown Current	I _{PDN}	PU / PD current is not included		90	130	µA
Internal PU/PD Res.	R _{PUPD}			60		kOhm
Input Voltage Low	V _{INL}				0.3 x V _{DD}	V
Input Voltage High	V _{INH}		0.7 x V _{DD}			V
I²C Clock Frequency	F _{I2C}				400	kHz
SPI Clock Frequency	F _{SPI}				10	MHz
FLASH Size		512 pages (32 x 32 bit)		64		kByte
FLASH Retention		85°C	10			years
FLASH Endurance		25°C	10k			

(1) All voltage values are with respect to network ground terminal.

12.3 FLASH IP 512 kbit

The embedded FLASH is a 512 kbit (64 kByte) memory. It has 512 pages, each of which has 32 x 32 bit data words. The memory within the ASIC can be read or written through the SPI or I²C interface.

Table 18: Parameter FLASH IP 512kbit

Parameter	Condition	Min	Typ	Max	Unit
Memory Size	512 row x 1024 column		512		kbit
Read Access Time				48	ns
Page Buffer Erase / Write			128		Byte
Parallel Input Bus			32		bit
Parallel Output Bus			32		bit
Read Current	20MHz		3.0		mA
Standby Current			20	30	μA
Powerdown Current			1	10	μA
Read Temperature		-40		85	°C
Data Retention	85°C	10			years
Data Endurance	25°C	10k			
Power-Up Time				20	μs
Power-Down Time				5	μs
Reset (RSTB) Disable Time				100	μs
Discharge Time				20	μs

12.4 Power-On-Reset

The power on reset monitors the internal supply voltage (VDD15) and releases the reset signal to the finite state machine when the voltage has reached a certain level. If the voltage drops below this threshold the state machine is reset again. A hysteresis and a short delay is implemented.

Table 19: Power-On-Reset

Parameter	Condition	Min	Typ	Max	Unit
POR Threshold		0.9		1.3	V
POR Hysteresis		100		140	mV
POR On-Delay			15		μs

13 SPI Communication with HS-FLASH

13.1 SPI Timings

A SPI protocol (SSEL is low active) is used to send / receive data. The chip operates always in slave mode with read data (MOSI) on rising edge and set data (MISO) on falling edge. An external μ Controller initiates a data transmission by setting SSEL from high to low and start toggling SCLK. After the transmission the SSEL must be set to high level.

Please note that the SSEL signal describes the internal voltage on the pad of the FLASH device. When the FLASH is supplied as an internal part of a Heimann Sensor HTPAd-device, the external *EE_Enable* pin is connected via a logic negation to the SSEL signal. Therefore, if low is applied to *EE_Enable* the SSEL gets high.

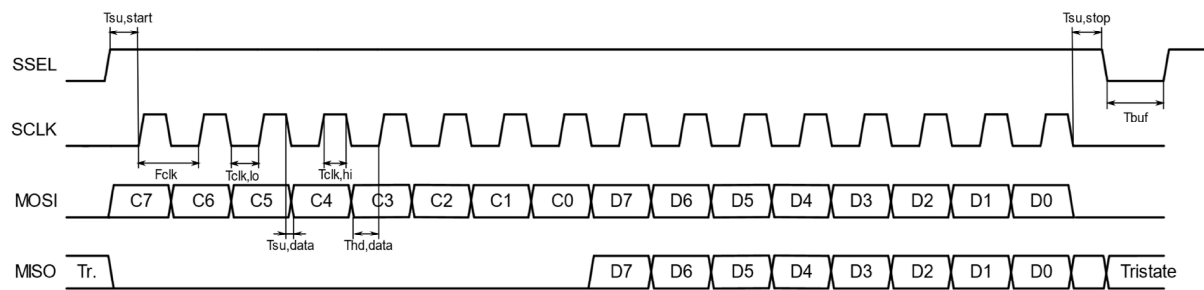


Figure 12: SPI Timings

Table 20: SPI Timings

Parameter	Description	Min	Typ	Max	Unit
Fclk	SPI clock frequency			10	MHz
Tclk,lo	low pulse duration	30			ns
Tclk,hi	high pulse duration	40			ns
Tsu,data	data set up time	30			ns
Thd,data	data hold time	10			ns
Tsu,start	clk set up start time	50			ns
Tsu,stop	clk set up stop time	50			ns
Tbuf	time between STOP / START	200			ns

13.2 SPI Protocol

The chip uses an 8 bit command for accessing configuration and FLASH interface. In case of a write access to an internal register the command is followed by zero, one or more data byte(s).

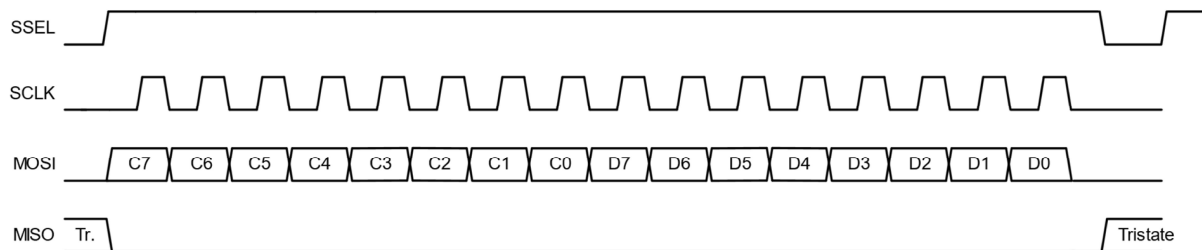


Figure 13: SPI Write Command

To read data from the chip, the command must be sent first. The command initiates the read sequence and the first bit of read bytes will be set on MISO with the falling edge of SCLK after last command bit. As many bytes as required consecutively can be read.

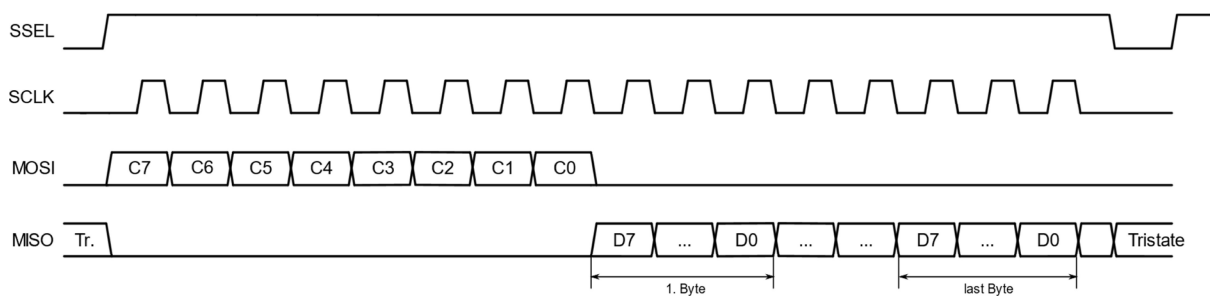


Figure 14: SPI Read Command

Table 21: SPI Commands

Name	CMD	R/W	Comment
FLASH_STANDBY	0x10	W	release reset and disable power down (100 μs reset disable time and 20 μs power down disable time)
FLASH_POWERDOWN	0x11	W	deep power saving mode
FLASH_ACTIVE	0x20	W	releases all signals to default state and enable FLASH
SET_ADDR	0x90xxxx	W	followed by 14-bit address MSB first (9-bit Page / 5-bit Column address)
SET_DATA	0xA0xxxxxxxx	W	followed by 32-bit data MSB first
READ_DATA	0xB00000	W	loads 32-bit data into SPI-block
GET_DATA	0xB1xxxxxxxx	R	reads out 32-bit data via SPI

13.3 FLASH Address Selection

Table 22: SET_ADDR Register (write only)

Addr / CMD	0x90															
SET_ADDR	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	Page Add [13:5]											Column Add [4:0]				
Default	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

14 Example Sequences

14.1 Read Whole FLASH (SPI and I²C)

FLASH_STANDBY (0x10)

Wait 100µs

FLASH_ACTIVE (0x20)

Wait 20µs

Repeat (16384) {

 SET_ADDR (0x90xxxx)

 READ_DATA (0xB00000)

 GET_DATA (0xB1xxxxxxxx)

}

FLASH_STANDBY (0x10)

14.2 Read/Write Timings

Table 23: Read / Write Timings

SPI (10MHz)	I ² C (400kHz)	Read / Write Operation
0.3s	6.0s	read whole FLASH
-	1.5s	continuous Read whole FLASH

14.3 SPI Example Sequences – Init and Read Thermopile Array

CONFIG_REG	WAKEUP
0x01	0x01

TRIM_REG1	MBIT_TRIM
0x03	0x0C

TRIM_REG2	BIAS_TRIML
0x05	0x0C

TRIM_REG3	BIAS_TRIMR
0x05	0x0C

TRIM_REG4	CLK_TRIM
0x06	0x14

CONFIG_REG	START WAKEUP
0x01	0x09

STATUS_REG	STATUS
0x02	??

wait 30 ms

STATUS_REG	STATUS
0x02	0x01

READ_DATA1	ATC1MSB	ATC1LSB	PTAT1MSB	PTAT1LSB	VDD1MSB	VDD1LSB	P0MSB	P0LSB	...	P239MSB	P239LSB
0x0A	??	??	??	??	??	??	??	??	...	??	??

READ_DATA1	ATC1MSB	ATC1LSB	PTAT1MSB	PTAT1LSB	VDD1MSB	VDD1LSB	P2340MSB	P2340LSB	...	P2219MSB	P2219LSB
0x0B	??	??	??	??	??	??	??	??	...	??	??

Start next conversion now.

15 Temperature Calculation

Below is a preliminary calibration, which is done for the 60x40d. Addresses and variables are subject to change.

The object and ambient temperature can be calculated from the sensor output and the stored calibration data. The table below is showing an overview of the flash.

60x40d	0x00	0x01	0x02	0x03	0x04	0x05	0x06	0x07	0x08	0x09	0x0A	0x0B	0x0C	0x0D	0x0E	0x0F
0x0000	PixCmn (float)			PixCmx (float)			gradScale		TN as 16 bit unsigned			epsilon				
0x0010									MBIT(calib)			BIAS(calib)		CLK(calib)		
0x0020				Arraytype			VDDTH1		VDDTH2							
0x0030				PTAT-gradient (float)			PTAT-offset (float)			PTAT (Th1)		PTAT (Th2)				
0x0040												VddScGrad		VddScOff		
0x0050				GlobalOff			GlobalGain									
0x0060	MBIT(user)		BIAS(user)		CLK(user)											
0x0070				DeviceID											NrOfDefPix	
0x0080	DeadPixAdr as 16 bit unsigned values															
0x0090	DeadPixAdr as 16 bit unsigned values															
0x00A0																
0x00B0	DeadPixMask															
0x00C0																
...																
0x4040	VddCompGrad stored as 16 bit sigend values															
...																
0x43F0	VddCompOff stored as 16 bit sigend values															
0x4400	VddCompOff stored as 16 bit sigend values															
...																
0x47B0	ThGrad _i stored as 16 bit signed values															
0x47C0	ThGrad _i stored as 16 bit signed values															
...																
0x5A70	ThOffset _i stored as 16 bit signed values															
0x5A80	ThOffset _i stored as 16 bit signed values															
...																
0x6D30	P _i stored as 16 bit unsigned values															
0x6D40	P _i stored as 16 bit unsigned values															
...																
0x7FF0																

Figure 15: FLASH overview 60x40d

All values are stored as unsigned 8 bit values, unless they are specified otherwise. The little endian format is used for larger values. Grey marked areas are used during calibration or for future use and are Heimann Sensor reserved.

MBIT(calib), BIAS(calib) and CLK(calib) are the settings for the registers, that have been used during calibration. **We recommend the usage of calibration settings of MBIT (stored in 0x1A), BIAS (0x1B) and CLK (0x1c).**

MBIT(user), BIAS(user) and CLK(user) are free to be set by the user.

The temperature calculation is only valid, if the same settings are used, that have been set during calibration!

TN is the table number and has to match the given table number in the sample code.

GlobalOff is stored as an 8 bit signed value, GlobalGain and VddCalib are both stored as 16 bit unsigned.

VDDTH1 and VDDTH2 is the used supply voltage during calibration measured by the sensor itself and stored in Digits.

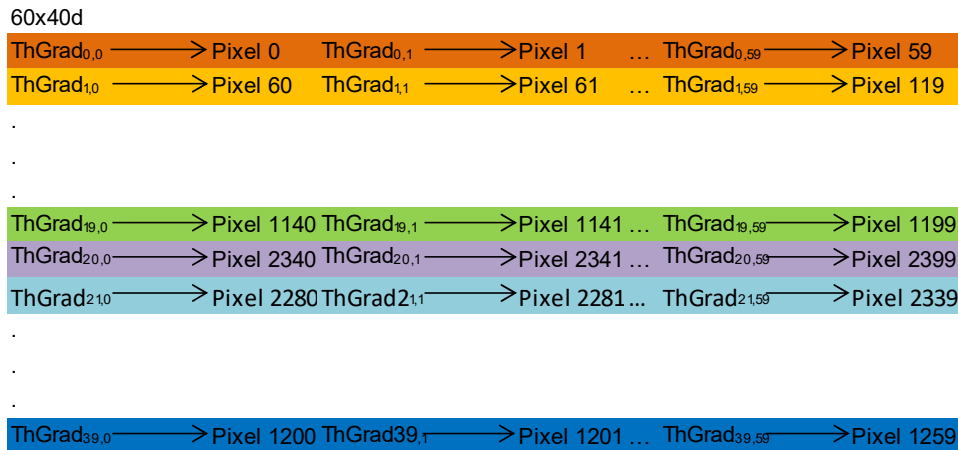


Figure 16: Readout order 60x40d

The order of $VddCompGrad_{ij}$ and $VddCompOff_{ij}$ is similar to the electrical Offsets and have to be used block by block.

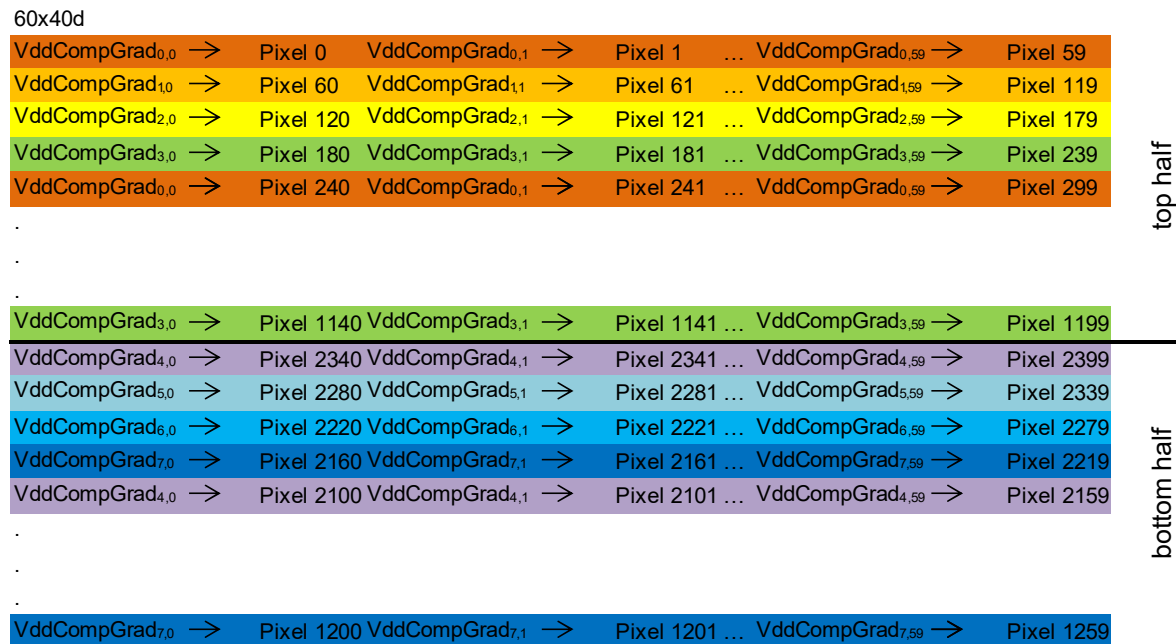


Figure 17: Readout order of VDDCompGrad 60x40d

15.1 Ambient Temperature

The ambient temperature (T_a) is calculated from the average measured PTAT value, the $PTAT_{gradient}$ and the $PTAT_{offset}$. It is recommended to use a stack buffer for the PTAT values in order to get a more stable ambient temperature result.

$$T_a = PTAT_{av} \cdot PTAT_{gradient} + PTAT_{offset} \quad (\text{Value is given back in } \mu\text{K})$$

where:

$PTAT_{gradient}$	is the gradient of the PTAT stored in the FLASH as a float value
$PTAT_{offset}$	is the offset of the PTAT stored in the FLASH as a float value
$PTAT_{av} = \frac{\sum_{i=0}^9 PTAT_i}{10}$	is the average measured PTAT value

15.2 Thermal Offset

The thermal offset of the sensor needs to be subtracted for each pixel to compensate for any thermal drifts.

$$V_{ij_Comp} = V_{ij} - \frac{ThGrad_{ij} \cdot PTAT_{av}}{2^{gradScale}} - ThOffset_{ij}$$

where:

ij	represents the row (i) and column (j) of the pixel
V_{ij_Comp}	is the thermal offset compensated voltage
V_{ij}	is the raw pixel data (digital), readout from the RAM
$ThGrad_{ij}$	is the thermal gradient, stored in the FLASH from 0x1C00 to 0x2FF0
$ThOffset_{ij}$	is the thermal offset, stored in the FLASH from 0x3000 to 0x57F0
$gradScale$	is the scaling coefficient for the thermal gradient stored in the FLASH

15.3 Electrical Offset

The electrical offset is used to compensate changes in the supply voltage. This compensation is only a subtraction so it can be done before or after the thermal offset compensation (here done afterwards). It is recommended to use an electrical offset stack in order to get a more stable electrical offset result and a more stable temperature result at the end. The electrical offsets should be sampled every 8th to 10th frame.

The compensation for the top half is done by using the following formula:

$$V_{ij_Comp} * = V_{ij_Comp} - elOffset[(j + i \cdot 60) \% 240]$$

and the bottom half analogue with this formula:

$$V_{ij_Comp} * = V_{ij_Comp} - elOffset[(j + i \cdot 60) \% 240 + 240]$$

where:

ij	represents the row (i) and column (j) of the pixel and electrical offset
$V_{ij_Comp}^*$	is the thermal and electrical offset compensated voltage
V_{ij_Comp}	is the thermal offset compensated voltage
$elOffset_{ij}$	is the electrical offset belonging to Pixel ij
$i\%:240$	is the rest of the integer division of i by 240 (e.g. 242:240=2)

15.4 Vdd Compensation

A supply voltage compensation called VddComp is used to take care of supply voltage changes. In order to use this compensation the supply voltage of the sensor (Vdd) has to be measured by the sensor from time to time by setting the configuration register and the average of Vdd 1 and Vdd 2 is resulting in Vdd (similar like $PTAT_{av}$). It is recommended to use a VDD stack buffer, in order to get a more stable VDD value. The stack should be similar to the PTAT stack.

The compensation for the top half is done by using the following formula:

$$VDD_{av} = \frac{\sum_{i=0}^9 VDD_i}{10}$$

$$V_{ijVDDComp} = V_{ijComp}^*$$

$$- \frac{\left(\frac{VddCompGrad[(j + i \cdot 60)\%240] \cdot PTAT_{av}}{2^{VDDScGrad}} + VddCompOff[(j + i \cdot 60)\%240] \right)}{2^{VDDScOff}} \cdot \left(VDD_{av} - VDD_{TH1} - \left(\frac{VDD_{TH2} - VDD_{TH1}}{PTAT_{TH2} - PTAT_{TH1}} \right) \cdot (PTAT_{av} - PTAT_{TH1}) \right)$$

and the bottom half analogue with this formula:

$$V_{ijVDDComp} = V_{ijComp}^*$$

$$- \frac{\left(\frac{VddCompGrad[(j + i \cdot 60)\%240 + 240] \cdot PTAT_{av}}{2^{VDDScGrad}} + VddCompOff[(j + i \cdot 60)\%240 + 240] \right)}{2^{VDDScOff}} \cdot \left(VDD_{av} - VDD_{TH1} - \left(\frac{VDD_{TH2} - VDD_{TH1}}{PTAT_{TH2} - PTAT_{TH1}} \right) \cdot (PTAT_{av} - PTAT_{TH1}) \right)$$

where:

ij	represents the row (i) and column (j) of the pixel
$V_{ij_VDDComp}$	is the Vdd compensated voltage

$V_{ij_Comp}^*$	is the thermal and electrical offset compensated voltage
$VddComGrad[ij]$	is the VddComp gradient belonging to Pixel ij
$VddComOff[ij]$	is the VddComp offset belonging to Pixel ij
$i\%240$	is the rest of the integer division of i by 240 (e.g. $242\%240=2$)
VDD_{av}	is the average measured supply voltage of the sensor in Digits
$VddScGrad$	is a scaling coefficient and stored in the FLASH 0x4E
$VddScOff$	is a scaling coefficient and stored in the FLASH 0x4F
VDD_{TH1}	is the supply voltage during calibration 1 stored in the FLASH 0x26, 0x27
VDD_{TH2}	is the supply voltage during calibration 2 stored in the FLASH 0x28, 0x29
$PTAT_{TH1}$	is the PTAT value of calibration 1 stored in the FLASH 0x3C, 0x3D
$PTAT_{TH2}$	is the PTAT value of calibration 2 stored in the FLASH 0x3E, 0x3F

15.5 Object Temperature

The calculation of the object temperature is done by using a look-up table and doing a bi-linear interpolation, the matching table is given by the table number (TN). The table is supplied in a separate file named "Table.c". If you do not have the file, please ask Heimann Sensor for support.

The sensitivity coefficients ($PixC_{ij}$) are calculated in the following way:

$$PixC_{ij} = \left(\frac{P_{ij} \cdot (PixC_{max} - PixC_{min})}{65535} + PixC_{min} \right) \cdot \frac{\epsilon}{100} \cdot \frac{GlobalGain}{10000}$$

where:

$PixC_{ij}$	is the sensitivity coefficient for each pixel
P_{ij}	is the stored sensitivity coefficient scaled to 16 bit
$PixC_{min}$	is the minimum sensitivity coefficient, used for scaling
$PixC_{max}$	is the maximum sensitivity coefficient, used for scaling
ϵ	is the emissivity factor
$GlobalGain$	is a factor for fine tuning of the sensitivity for all Pixel

Leading to a compensation of the pixel voltage

$$V_{ij_PixC} = \frac{V_{ij_VDDComp} \cdot PCSCALEVAL}{PixC_{ij}}$$

where:

V_{ij_PixC}	is the sensitivity compensated IR voltage
$PCSCALEVAL$	is a defined scaling coefficient, typically set to $1 \cdot 10^8$

16 Example Calculation

Example values:

$$PTAT_{av} = \frac{\sum_{i=0}^9 PTAT_i}{10} = 38152 \text{ Digits}$$

$$PTAT_{gradient} = 0.0211 \text{ dK/Digit}$$

$$PTAT_{offset} = 2195.0 \text{ dK}$$

$$V_{00} = 34435 \text{ Digits}$$

$$elOffset[0] = 34240$$

$$gradScale = 17$$

$$THGrad_{00} = 87 \rightarrow \text{signcheck } 87$$

$$THOffset_{00} = 65506 \rightarrow \text{signcheck } -30$$

$$VDD_{av} = 35000$$

$$VDD_{TH1} = 33942$$

$$VDD_{TH2} = 36942$$

$$PTAT_{TH1} = 30000$$

$$PTAT_{TH} = 42000$$

$$VddCompGrad[0] = 10356 \rightarrow \text{signcheck } 10356$$

$$VddCompOff[0] = 51390 \rightarrow \text{signcheck } -14146$$

$$VddScGrad = 16$$

$$VddScOff = 23$$

$$PixC_{00} = 1.087 \cdot 10^8$$

$$PCSCALEVAL = 1 \cdot 10^8$$

Calculation of ambient temperature:

$$T_a = PTAT_{av} \cdot PTAT_{gradient} + PTAT_{offset} = 38152 \cdot 0.0211 + 2195.0 \text{ dK} = 3000 \text{ dK}$$

Compensation of thermal offset:

$$V_{00_Comp} = V_{00} - \frac{ThGrad_{00} \cdot PTAT_{av}}{2^{gradScale}} - ThOffset_{00} = 34435 - \frac{87 \cdot 38152}{2^{17}} - (-30) = 34439$$

Compensation of electrical offset:

$$V_{00_Comp}^* = V_{00_Comp} - elOffset[0] = 34439 - 34240 = 199$$

Compensation of supply voltage:

$$V_{ij_VDDComp} = V_{ij_Comp}^* - \frac{\left(\frac{VddCompGrad[0] \cdot PTAT_{av}}{2^{VddScGrad}} + VDDCompOff[0] \right)}{2^{VddScGrad}} \cdot \left(VDD_{av} - VDD_{Th1} - \left(\frac{VDD_{Th2} - VDD_{Th1}}{PTAT_{Th2} - PTAT_{Th1}} \right) \cdot (PTAT_{av} - PTAT_{Th1}) \right)$$

$$= 199 - \frac{\left(\frac{10356 \cdot 38152}{2^{16}} - 14146 \right) \cdot (35000 - 33942 \pm 2038)}{2^{23}} = 199 - (1) = 198$$

Table 24: Example look-up table

TA[dK]/dig	2882	3032	3182	3332
-64	1494	2128	2491	2775
-32	2466	2692	2898	3091
0	2882	3032	3182	3332
32	3170	3285	3406	3530
64	3396	3491	3592	3699
96	3584	3665	3754	3848
128	3746	3818	3897	3981
160	3890	3954	4025	4102
192	4019	4078	4143	4214
224	4137	4191	4251	4317
256	4246	4296	4351	4413
288	4347	4393	4445	4503
320	4441	4485	4534	4588

$$V_{00_PixC} = \frac{198 \cdot 1 \cdot 10^8}{1.087 \cdot 10^8} = 182$$

Ta was calculated before to 3000 dK.

The matching region in the look-up table is already marked yellow, the bi-linear interpolation is leading to an object temperature of 4026 dK = (4026dK-2732dK)/10 = 129.4 °C.

A global Offset (GlobalOff) is used for fine tuning of the measured object temperature and has to be added to the object temperature. This value is stored in the FLASH.

16.1 Pixel Masking

A maximum of 12 defect Pixels are allowed on the complete array, this means that at least 99.5 % of the Pixels are working correctly. The amount of defect Pixels is given in the FLASH at address 0x007F and is named *NrOfDefPix*. *DeadPixAdr* is the address of the defect Pixels and *DeadPixMask* determines the neighbours that should be used for masking the pixel. A simple averaging of all selected nearest neighbours are done to overwrite the temperature value of these Pixel. Only the amount of pixels "*NrOfDefPix*" is stored in *DeadPixAdr*. These values are stored as 16 bit unsigned values. For example: If only one pixel has to be masked, then the other values of *DeadPixAdr* are set to 0.

The order of the top and bottom half is the same as the readout order. The neighbours to use is given in a binary format and the order is shown in the overview below in decimal and binary values for the top and bottom half.

$$adaptedAdr [i] = 2400 + 1200 - DeadPixAdr [i] + k[i] * 2 - 60$$

where:

adaptedAdr [i] is the adapted dead pixel address

k[i] is the column of the corresponsive pixel (for pixel number 2218 this would be 58)

$$adaptedAdr [i] = 2400 + 1200 - 2218 + 58 * 2 - 60 = 1438$$

top half

128	1	2
64	DeadPix	4
32	16	8

0b1000 0000	0b0000 0001	0b0000 0010
0b0100 0000	DeadPix	0b0000 0100
0b0010 0000	0b0001 0000	0b0000 1000

bottom half

32	16	8
64	DeadPix	4
128	1	2

0b0010 0000	0b0001 0000	0b0000 1000
0b0100 0000	DeadPix	0b0000 0100
0b1000 0000	0b0000 0001	0b0000 0010

Example values for the masking:

$$NrOfDefPix = 0x03$$

$$DeadPixAdr[0] = 0x002D \rightarrow \text{Pixel } 45$$

$$DeadPixAdr[1] = 0x031F \rightarrow \text{Pixel } 799$$

$$DeadPixAdr[2] = 0x08AA \rightarrow \text{Pixel } 2218 \text{ (read – out pixel) actual pixel number is } 1438$$

$$DeadPixMask[0] = 0x7C \rightarrow 0b01111100(\text{top})$$

$$DeadPixMask[1] = 0x8F \rightarrow 0b10001111(\text{top})$$

$$DeadPixMask[2] = 0xFE \rightarrow 0b11111110(\text{bot})$$

According to the sample values 3 Pixels are defect and need to be interpolated. 2 Pixels are on the top and 1 Pixel on the bottom half. Assuming, that the neighbouring Pixels are having the temperature data stated below and the green marked cells are used for averaging (according to DeadPixMask), then the interpolated temperature will be the following:

All values are given in dK

3007	Pixel 45	3008
3008	3011	3009

Pixel 44	Pixel 45	Pixel 46
Pixel 124	Pixel 125	Pixel 126

3010	3012	3005
3007	Pixel 799	3008
3008	3011	3009

Pixel 718	Pixel 719	Pixel 720
Pixel 798	Pixel 799	Pixel 800
Pixel 878	Pixel 879	Pixel 880

3010	3012	3005
3007	Pixel 1438	3008
3008	3011	3009

Pixel 1377	Pixel 1378	Pixel 1379
Pixel 1437	Pixel 1438	Pixel 1439
Pixel 1497	Pixel 1498	Pixel 1499

If a pixel is masked, the adjacent neighbours must have not more than 4 dead pixels in serial order, if you check them clockwise (or the other way around):

OK		
0	1	0
0	0	1
1	0	0

OK		
0	1	0
0	0	1
0	0	1

NOK		
0	1	1
0	0	1
0	0	0

16.2 Look-up Table

The matching look-up table has to be taken from the "Table.c" file. Here is just shown an exemplary data for one optic.

Table with columns labeled 'dig. I, Ta[dK]' and rows of numerical data. A 'To in dK' label is present in the first few rows of the left table.

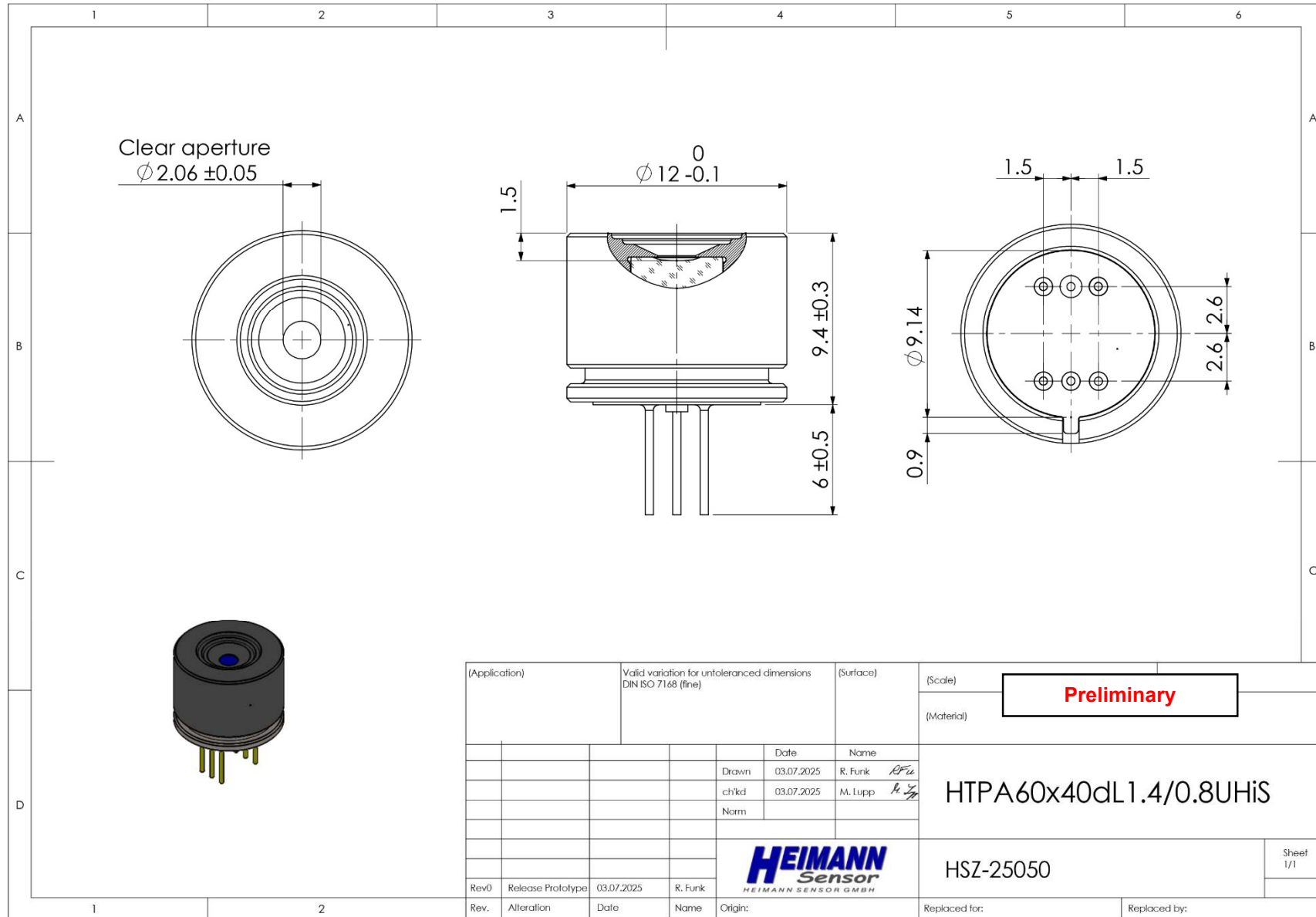
17 Order Code Chart

HTPA60x40d	R1	L1.4/0.8	UHi	A	(USB)
HTPA60x40d	R1	L1.4/0.8	UHi	A	(UDP)
HTPA60x40d	R1	L1.4/0.8	UHi	M	(PoE)
HTPA60x40d	R1	L1.4/0.8	UHi	M	(UDP)
HTPA60x40d	R1	L1.4/0.8	UHi	C	
HTPA60x40d	R1	L1.9/0.8	UHi	A	(USB)
HTPA60x40d	R1	L1.9/0.8	UHi	A	(UDP)
HTPA60x40d	R1	L1.9/0.8	UHi	M	(PoE)
HTPA60x40d	R1	L1.9/0.8	UHi	M	(UDP)
HTPA60x40d	R1	L1.9/0.8	UHi	C	
HTPA60x40d	R1	L2.6/1.0	UHi	A	(USB)
HTPA60x40d	R1	L2.6/1.0	UHi	A	(UDP)
HTPA60x40d	R1	L2.6/1.0	UHi	M	(PoE)
HTPA60x40d	R1	L2.6/1.0	UHi	M	(UDP)
HTPA60x40d	R1	L2.6/1.0	UHi	C	
HTPA60x40d	R1	L4.0/0.8F6.0	UHi	A	(USB)
HTPA60x40d	R1	L4.0/0.8F6.0	UHi	A	(UDP)
HTPA60x40d	R1	L4.0/0.8F6.0	UHi	M	(PoE)
HTPA60x40d	R1	L4.0/0.8F6.0	UHi	M	(UDP)
HTPA60x40d	R1	L4.0/0.8F6.0	UHi	C	

Bold: Selectable options

Regular: Fixed/Not selectable

18 Outer Dimension



(Application)		Valid variation for untoleranced dimensions DIN ISO 7168 (fine)		(Surface)		(Scale)	Preliminary		
						(Material)			
				Date	Name	HTPA60x40dL1.4/0.8UHIS			
				Drawn	03.07.2025			R. Funk	<i>RF</i>
				chkd	03.07.2025			M. Lupp	<i>ML</i>
				Norm					
				HEIMANN Sensor HEIMANN SENSOR GMBH		HSZ-25050			
Rev0	Release Prototype	03.07.2025	R. Funk					Sheet 1/1	
Rev.	Alteration	Date	Name	Origin:	Replaced for:		Replaced by:		